

**CHIP PACKAGE WITH MULTIPLE CHIPS CONNECTED BY BUMPS**

Appl. No. : 10/695,630 Confirmation No. 5386  
Applicant : Shih-Hsiung Lin,  
Mou-Shiung Lin  
Filed : October 27, 2003  
TC/A.U. : 2826  
Examiner : WILLIAMS, ALEXANDER O  
Docket No. : MEGP0005USA4  
Customer No. : 27765

Commissioner for Patents  
P.O. Box 1450  
Alexandria VA 22313-1450

**AMENDMENT**

Sir:

- 5 In response to the Office action of November 06, 2006, please amend the above-identified application as follows:

**Amendments to the Claims** are reflected in the listing of claims which begins on page 2 of this paper.

**Remarks/Arguments** begin on page 13 of this paper.